


- ① Substrate: 1.59mm  $\pm$ 0.18mm [0.0625"  $\pm$ 0.007"]  
FR4/G10 or equivalent high temp material;  
Non-clad
- ② Pins: material- Brass Alloy 360 1/2 hard; finish-  
0.25 $\mu$ m [10 $\mu$ ] Au over 1.27 $\mu$ m [50 $\mu$ ] Ni (min.).
- ③ Solder Balls: Sn96.5Ag3.0Cu0.5



**Description:** Giga-snaP BGA SMT Foot

107 position terminal pins (0.8mm centers, 10x14 array) to SMT solder balls (BGA type). Pin assignment 1:1.

**Tolerances:** diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

|   |  |                         |                                       |                           |
|---|--|-------------------------|---------------------------------------|---------------------------|
|  <p>© 2008 IRONWOOD ELECTRONICS, INC.<br/>Tele: (800) 404-0204<br/>www.ironwoodelectronics.com</p> | <p><b>SF-BGA107D-B-61F Drawing</b></p> | <p>Status: Released</p> | <p>Scale: 6:1</p>                     | <p>Rev: B</p>             |
|   | <p>Drawing: J. Glab</p>                | <p>Date: 02/04/08</p>   | <p>File: SF-BGA107D-B-61F Dwg.mcd</p> | <p>Modified: 07/02/14</p> |